

## PATENT ASSIGNMENT

Electronic Version v1.1  
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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	Assignment of a Half Interest in the Patents and Patent Applications
CONVEYING PARTY DATA	
Name	Execution Date
Siargo Ltd.	08/10/2011
RECEIVING PARTY DATA	
Name:	M-Tech Instrument Corporation (Holding) Limited
Street Address:	363 Java Road, North Point
Internal Address:	23rd Floor
City:	Hong Kong
State/Country:	HONG KONG
PROPERTY NUMBERS Total: 9	
Property Type	Number
Patent Number:	7797997
Patent Number:	7765679
Patent Number:	7752910
Patent Number:	7536908
Patent Number:	7878056
Patent Number:	7908096
Application Number:	12538337
Application Number:	12562979
Application Number:	13035639
CORRESPONDENCE DATA	
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>	
Correspondent Name:	Emil Chang, Venture Pacific Law, PC

OP \$360.00 7797997

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ATTORNEY DOCKET NUMBER:	SIARGO-M-TECH_ASSIGNMENTS
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NAME OF SUBMITTER:	Quon Hom
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Total Attachments: 4  
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# ASSIGNMENT

THIS ASSIGNMENT is dated 10 August 2011 and made between:

- (1) **SIARGO LTD**, a company incorporated in the Cayman Islands (registered number CR-130662) whose registered office is at P.O. Box 897, 3rd Floor One Capital Place, Shedden Road, George Town, Grand Cayman, KY1-1103 ("**Assignor**");

and

- (2) **M-TECH INSTRUMENT CORPORATION (HOLDING) LIMITED** 卓度儀表(控股)有限公司, a company incorporated in Hong Kong (registered number 1612877) whose registered office is at 23rd Floor, 363 Java Road, North Point, Hong Kong ("**Assignee**")

(collectively the "**Parties**").

WHEREAS:-

- (A) The Assignor is the sole legal and beneficial owner of the pending applications or registrations for the patents, utility models and designs set forth in the attached Schedule ("**Patents**").
- (B) The Assignor has agreed to transfer and assign one-half (50%) of its rights and interest in the Patents to the Assignee for the consideration hereinafter set forth.

NOW THIS ASSIGNMENT WITNESSETH as follows:-

1. In consideration of the sum of One Hundred Hong Kong Dollars (HKD100) now paid by the Assignee to the Assignor (receipt of which the Assignor hereby acknowledges), the Assignor hereby transfers and assigns unto the Assignee one-half (50%) of its right, property titles and interest whatsoever in the Patents and to the intent that the Assignor and the Assignee shall jointly own an equal one-half (50%) interest in the Patents.
2. The Assignee shall be responsible to maintain the Patents by paying the annual fees and shall seek reimbursement of half (50%) of all costs and expenses of doing so from the Assignor.
3. This Assignment shall be governed by the laws of Hong Kong Special Administrative Region.

## **Schedule**

### **US Patents**

1. Configuration and methods for manufacturing time-of-flight MEMS mass flow sensor, US patent no. 7797997, September 21, 2010;
2. Method of manufacturing a flow rate sensor, US patent no. 7765679, August 3, 2010;
3. Micromachined mass flow sensor and method of making the same, US patent no. 7752910, July 13, 2010;
4. Micromachined thermal mass flow sensors and insertion type flow meters and manufacture methods, US patent no. 7536908, May 26, 2009;
5. Micromachined thermal mass flow sensor with self-cleaning capability and method of making the same, US patent no. 7878056, Feb 1, 2011;
6. Integrated micromachined thermal mass flow sensor and methods of making the same, US patent no. 7908096, Mar 15, 2011.

### **PCT Patent**

1. Configuration and methods for manufacturing time-of-flight MEMS mass flow sensor, WO/2009/029236, May 3, 2009. (US patent no. 7797997)

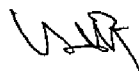
### **US Patent Applications**

1. Robust micromachining thermal mass flow sensor and method of making the same. Application #12/538,337;
2. Method of forming metal interconnection on thick polyimide film. Application #12/562,979;
3. MEMS time-of-flight mass flow meter. Application #13/035,639.

The Parties hereto have executed this Assignment the date and year first before written.

SIGNED for and on behalf of )

SIARGO LTD. )



Name: Liji Huang

Title: Director

SIGNED for and on behalf of )

M-TECH INSTRUMENT )

CORPORATION (HOLDING) )

LIMITED 卓度儀表(控股)有限公司 )

Name:

Title:

The Parties hereto have executed this Assignment the date and year first before written.

SIGNED for and on behalf of

**SIARGO LTD.**

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Name:

Title:

SIGNED for and on behalf of

**M-TECH INSTRUMENT  
CORPORATION (HOLDING)  
LIMITED 卓度儀表(控股)有限公司**

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Name: KWAN YUK CHOI

Title: DIRECTOR